



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: Wongsenakhum et al.

Attorney Docket No.:  
NOVLP096/NVLS-2902

Application No.: 10/815,560

Examiner: Estrada, M.

Filed: March 31, 2004

Group: 2823

Title: METHOD OF FORMING LOW-  
RESISTIVITY TUNGSTEN  
INTERCONNECTS

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on October 12, 2005 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed: \_\_\_\_\_

Tara Hayden

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE A**

Dear Sir:

This is response to the Office Action mailed on July 12, 2005 in the above-identified application. Please amend the application as follows:

Amendments to the Claims are reflected in the **Listing of Claims** that begins on page 2 of this paper.

**Remarks** begin on page 8 of this paper.

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02 FC:1202

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